



SMC-01-1457

December 17, 2003

To: Commissioner for Patents  
P.O.Box 1450  
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Subject: | Serial No. 10/672,403 09/26/03 |

Ta-Chin Lin et al.

ALGORITHMS TUNNING FOR DYNAMIC LOT  
DISPATCHING IN WAFER AND CHIP PROBING

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#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on December 19, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

S.B.A 12/19/03

U.S. Patent 6,256,548 to Lin, "Method for Controlling Lots Dispatches of Tool Groups," discloses a method for controlling lots dispatches of tool groups.

U.S. Patent 5,841,677 to Yang et al., "Method and Apparatus for Dispatching Lots in a Factory," discloses a method for dispatching lots in a factory.

U.S. Patent 5,612,886 to Weng, "Method and System for Dynamic Dispatching in Semiconductor Manufacturing Plants," discloses a method for dynamic dispatching lots in a factory.

U.S. Patent 5,950,170 to Pan et al., "Method to Maximize Capacity in IC Fabrication," discloses a method to maximize throughput of a group of multiprocess machines whereby the number of each kind of machine is determined.

U.S. Patent 5,889,673 to Pan et al., "Manufacturing Method and System for Dynamic Dispatching of Integrated Circuit Wafer Lots," discloses a process control of manufacturing of integrated circuit (IC) chips.

U.S. Patent 5,721,686 to Shahraray et al., "Method and Apparatus for Control and Evaluation of Pending Jobs in a Factory," discloses a system and method for optimizing the scheduling of jobs in a factory.

U.S. Patent 5,546,326 to Tai et al., "Dynamic Dispatching Rule That Uses Long Term Due Date and Short Term Queue Time to Improve Delivery Performance," discloses a dynamic dispatching method for delivery performance by a factory.

U.S. Patent 5,818,716 to Chin et al., "Dynamic Lot Dispatching Required Turn Rate Factory Control System and Method of Operation Thereof," discusses how a dispatching algorithm named "Required Turn Rate (RTR)" functions according to the level of current wafers in process (WIP) algorithm revising the due date for every lot to satisfy the demand from Master Production Scheduling (MPS).

U.S. Patent 5,751,580 to Chi, "Fuzzy Logic Method and System for Adjustment of Priority Rating of Work in Process in a Production Line," discusses in a manufacturing control system for computer control of work flow in an automatic manufacturing production line with a plurality of work stations at which the progress of work is monitored, priority ratings are assigned to each lot or WIP materials with the priority ratings ranging from low to high.

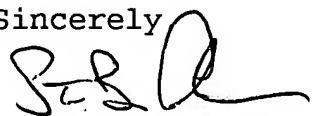
U.S. Patent 5,748,478 to Pan et al., "Output Management of Processing in a Manufacturing Plant," discloses scheduling systems for fabrication and manufacturing plants for the fabrication of integrated circuits.

U.S. Patent 5,826,238 to Chen et al., "Daily Target Generation and Machine Allocation with Priority," discloses a method and system for operating a data processing system including a data base computer system and a resource allocation computer for control of resource allocation in a manufacturing plant with a manufacturing line.

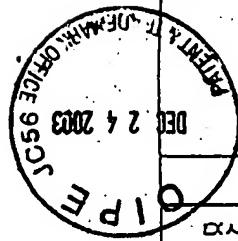
U.S. Patent 6,256,550 to Wu et al., "Overall Equipment Effectiveness On-Line Categories System and Method," discloses a manufacturing control and reporting method/system for manufacture of semiconductor devices.

U.S. Patent 5,696,689 to Okumura et al., "Dispatch and Conveyer Control System for a Production Control System of a Semiconductor Substrate," discusses a production control system applied to a process for manufacturing semiconductor substrates.

Sincerely



Stephen B. Ackerman,  
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INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION (Use several sheets if necessary)				Document Number (Specified) <b>TSMC-01-1457</b>	Application Number <b>101672,403</b>		
				Applicant <b>Ta-Chin Lin et al.</b>			
				Filing Date <b>09/26/03</b>	Drawn At U.S. Office <b>09/26/03</b>		
U. S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE	
	6256548	7/3/01	Liu	700	121	5/8/98	
	5841677	11/24/98	Yang et al.	364	569	5/21/97	
	5612886	3/18/97	Weng	364	468.07	5/12/95	
	5950170	9/7/99	Pan et al.	705	7	4/11/97	
	5889673	3/30/99	Pan et al.	364	468.03	12/27/96	
	5721686	2/24/98	Shahravan et al.	364	468.08	10/31/96	
	5546326	8/13/96	Tai et al.	364	552	4/4/95	
	5818716	10/6/98	Chin et al.	364	468.06	10/18/96	
	5751580	5/12/98	Chi	364	468.07	7/26/96	
	5748478	5/5/98	Pan et al.	364	468.05	3/17/97	
	5826238	10/20/98	Chen et al.	705	8	4/21/96	
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
OTHER DOCUMENTS (Including Author, Title, Date, Page, Etc.)							
EXAMINER				DATE CONSIDERED			

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